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Case Docket No. 001522

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To the Director of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Norio FUKASAWA, Takashi HOZUMI and Toshimi KAWAHARA

Additional name(s) of conveying party(ies) attached? NO

2. Name and address of receiving party(ies):

09714648

Name: FUJITSU LIMITED

Street Address: 1-1, Kamikodanaka 4-chome, Nakahara-ku

Kawasaki-shi, Kanagawa 211-8588, JAPAN

Additional name(s) & address(es) attached? NO

3. Nature of conveyance: Assignment

Execution Date: November 2, 2000

- 4. Title: SEMICONDUCTOR DEVICE HAVING INCREASED RELIABILITY AND METHOD OF PRODUCING THE SAME AND SEMICONDUCTOR CHIP SUITABLE FOR SUCH A SEMICONDUCTOR DEVICE AND METHOD OF PRODUCING THE SAME
- 5. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: November 2, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional nymbers attached? NO

40.00 OP

ga FC:581

PATENT REEL: 013188 FRAME: 0761 6. Name and address of party to whom correspondence concerning document should be mailed: Name: Armstrong, Westerman, Hattori, McLeland & Naughton **Suite 1000** 1725 K Street, N.W. Washington, D.C. 20006 7. Total number of applications and patents involved: 1 8. Total fee (37 CFR 3.41). \$ 40.00 XX Check enclosed 9. Deposit Account No.: **01-2340** 10. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Date <u>November 17, 2000</u> Reg. No.: 27,132

Total number of pages including cover sheet: 3

DWH/II

PATENT REEL: 013188 FRAME: 0762

(Insert ASSIGNEE's Name(s) Address(es))

(Title of Invention)

(*If the assignment is

of the application, this section must be

completed)

(Signatures)

being filed after the filing

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		et No.
U.S. ASSIC	SNMENT	
	m of One Dollar (\$1.00), and of ed inventor(s) (hereinafter ASSIGNO	
FUJITSU LIMITED		
1-1, Kamikodanaka 4-chom 8588 Japan	e, Nakahara-ku, Kawasaki-s	shi, Kanagawa, 211-
	t of which is hereby acknowledged, to ASSIGNEE the entire and exclusi-	
	ING INCREASED RELIABILITY	
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	Patent of the United States was exec	
*filed on	, Serial No. McLeland & Naughton is hereby a ate hereon, when known)	uthorized to insert the series
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continuation, divisional, reissue or	e all papers necessary in connection reexamination applications thereof a applications as the ASSIGNEE may o	and also to execute separate
litigation, or other legal proceeding continuation, divisional, reissue or thereon and to cooperate with the	ute all papers necessary in connecting which may be declared concern reexamination thereof or Letters Pal ASSIGNEE in every way possible interference, litigation, or other legal	ing this application or any tent or reissue patent issued in obtaining and producing
IN WITNESS WHEREOF, the un	dersigned inventor(s) has (have) affix	ed his/her/their signature(s).
norio Fikusawa	Norio Fukasawa	November 2, 2000
(SIGNATURE)	(TYPE NAME)	(DATE)
Japashi Hogami (SIGNATURE)	Takashi Hozumi	November 2, 2000
	(TYPE NAME)	(DATE)
Tootume kaurahara (SIGNATURE)	Toshimi Kawahara	November 2, 2000
(SIGNATURE)	(TYPE NAME)	(DATE)

NO LEGALIZATION REQUIRED

(SIGNATURE)

(DATE)

(TYPE NAME)